技术数据表

特点（ ）：

目录

Catalogue

Catalogue

电性参数

Parameter	Symbol	Rating	Unit
Consumed power	Pd	70	mW
		20	mA
Peak Forward Current	IFp	80	mA
Operating ambient temperature	Topr	-20 C ~ +85 C	
Storage ambient temperature	Tstg	-40 C ~ +85 C	
Welding conditions	Tsol	reflow soldering 240°C 6s manual welding 300°C 3s 2.0mm	

亮度分档

：

代码	最小值	最大值	单位	测试条件
A9	1200	1500	mcd	IF=20mA
B1	1500	1800		
B2	1800	2100		

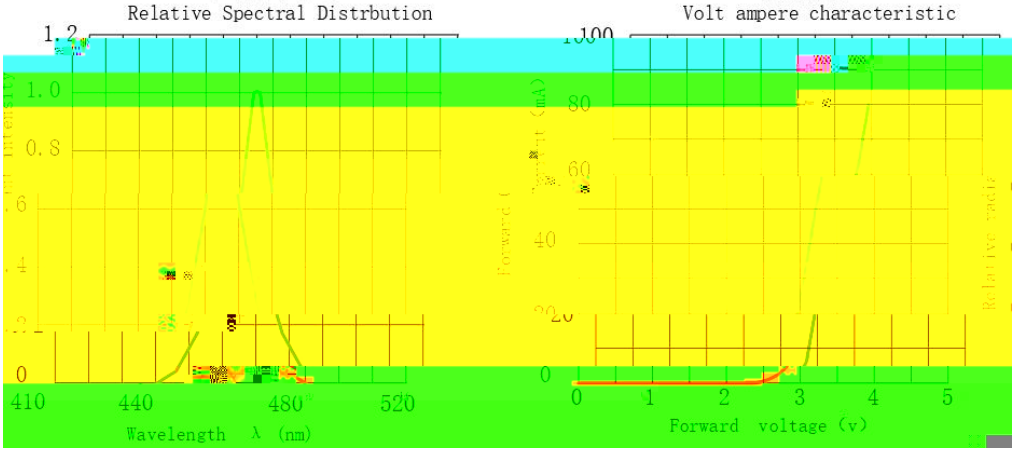
电压分档

：

波长分档

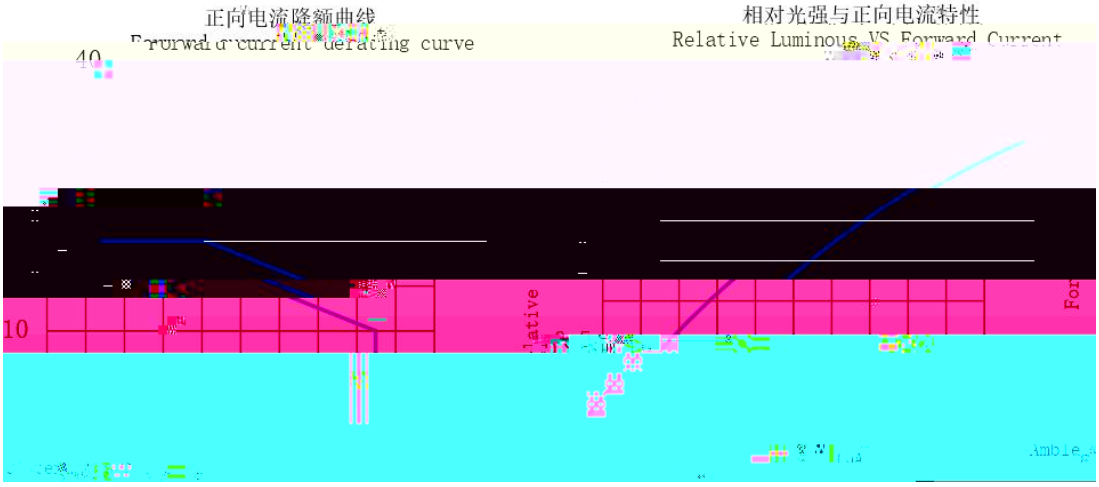
典型特性曲线

光谱分布曲线
Relative Spectral Distrbution



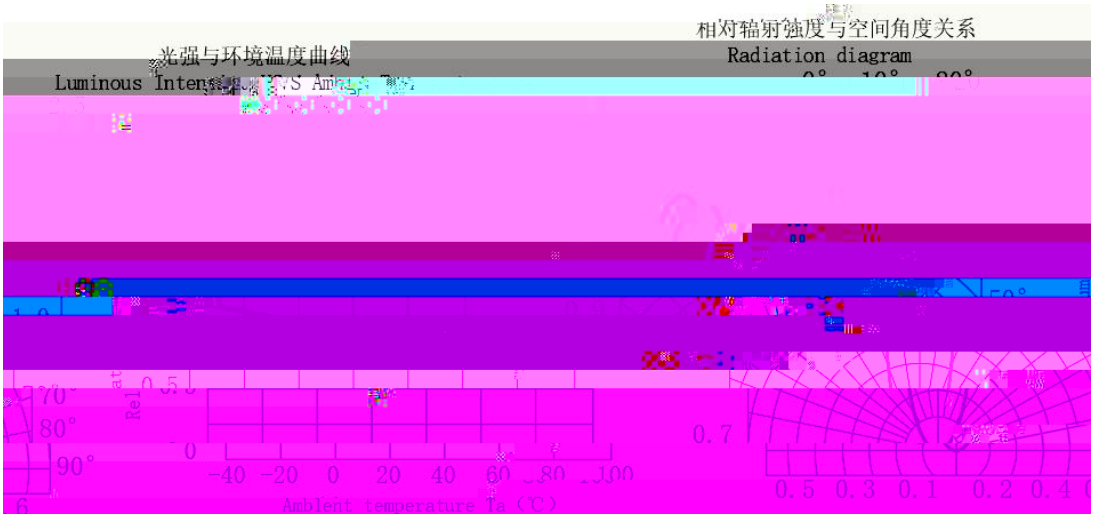
伏安特性
Volt ampere characteristic

正向电流降额曲线
Forward current derating curve



相对光强与正向电流特性
Relative Luminous VS Forward Current

光强与环境温度曲线
Luminous Intensity VS Ambient Temperature



相对辐射强度与空间角度关系
Radiation diagram

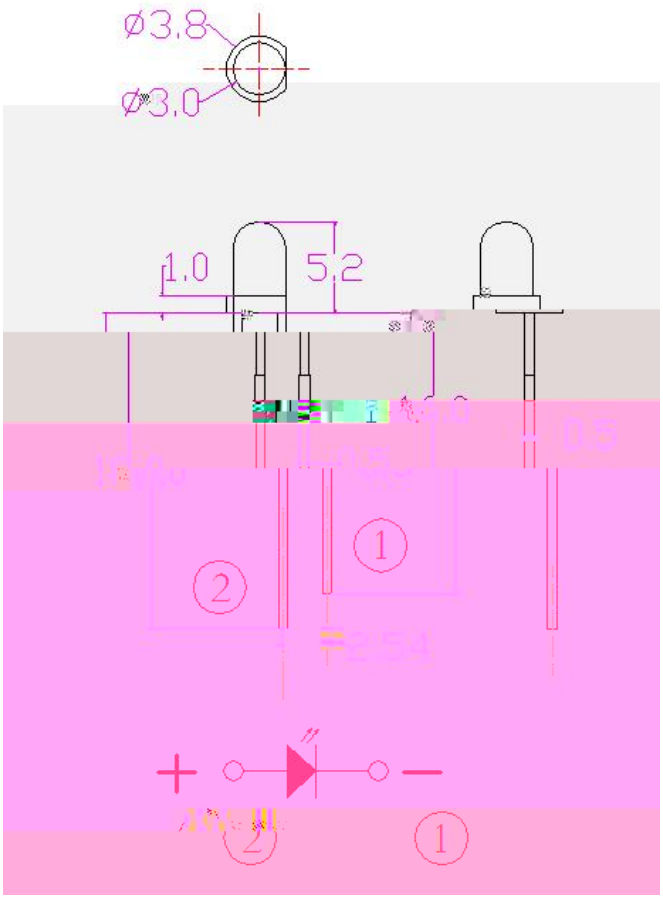
25±5 /Note If not otherwise indicated the test environment temp erature is 25±5

可靠性试验

Reliability Test Items And Conditions

Class	Test item	Testing environment	Testing time	Qty	Fail qty

外形尺寸

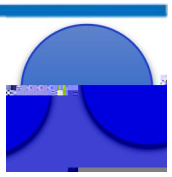


(Note)

Dimensions are in millimeters.

± 0.50

Tolerances unless mentioned are ĩ ɐe c Ã% ¦ ¦ u u# # E̮ ʞ



使用注意事项（ ）

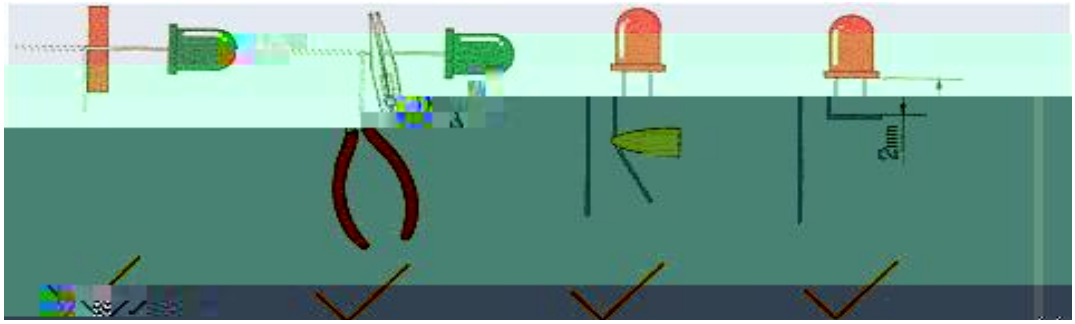
1.
LED

This LED can be used in some ordinary electronic equipment, such as office equipment, communication equipment, house decoration, if LED is used in some high reliability requirements, such as air transportation, traffic control and medical liao equipment, must refer to the information provided by sales.

Storage environment of LED with temperature not exceeding 30 and relative humidity not exceeding 70%.It is recommended that LDE be used in the original box for no more than three months. If longer storage time is required, put it in the drying box and add desiccant or filled with nitrogen.

Special care must be taken when cleaning colloids with chemicals, as some chemicals have damage to the colloidal surface and cause fading such as trichloroethylene, propylene, ketone, etc.It can be wiped and soaked with ethanol for no more than 3 minutes at room temperature.

1 2
It must be 2 mm from the colloid to bend the bracket.
2
Support forming must be done with fixtures or by a professional.
3
Support forming must be completed before welding.
4
The pins and spacing are the same as on the circuit board.
5 PCB LED
Welding must be performed at normal temperature and when LED is normally welded to the PCB plate, avoid applying mechanical pressure at LED pins at a minimum.



使用注意事项（ ）

使用注意事项（ ）

8、其他事项：

When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.